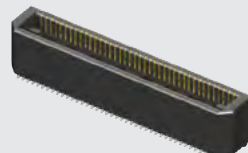
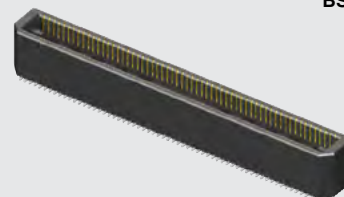




BSE-020-01-F-D-A



BTE-040-02-L-D-A



BTE-060-02-F-D-A

(0.80 mm) .0315"

BTE, BSE SERIES

BASIC BLADE & BEAM HEADER & SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?BTE or www.samtec.com?BSE

Insulator Material:

Liquid Crystal Polymer

Contact Material:

Phosphor Bronze

Plating: Au or Sn over

50 µ" (1.27 µm) Ni

Current Rating: 2 A per pin

(1 pin powered per row)

Operating Temp Range:

-55 °C to +125 °C

Voltage Rating: 225 VAC with

5 mm Stack Height

Max Cycles: 100

RoHS Compliant: Yes

PROCESSING

Lead-Free Solderable: Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (020-080)

(0.15 mm) .006" max (100-120)

Board Stacking:

For applications requiring more than two connectors per board or 80 positions or higher, contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594

MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(5.00) .197
-02	(8.00) .315

*Processing conditions will affect mated height.

ALSO AVAILABLE (MOQ Required)

- 30 µ" (0.76 µm) Gold
- Edge Mount Capability
- Friction Lock option
- 11 mm, 14 mm, 16.10 mm, 19.10 mm, 22 mm, 25 mm and 30 mm Stack Height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.)

Contact Samtec.

Note: Some lengths, styles and options are non-standard, non-returnable.

BTE	NO. OF POSITIONS PER ROW	LEAD STYLE	PLATING OPTION	D	A	OTHER OPTION
Mates with: BSE	-020, -040, -060, -080, -100, -120	Specify LEAD STYLE from chart	-F = Gold Flash on contact, Matte Tin on tail -L = 10 µ" (0.25 µm) Gold on contact, Matte Tin on tail -C* = Electro-Polished Selective 50 µ" (1.27 µm) min Au over 150 µ" (3.81 µm) Ni on Signal Pins in contact area, Matte Tin over 50 µ" (1.27 µm) min Ni on all solder tails			-K = (7.00 mm) .275" DIA Polyimide Film Pick & Place Pad -TR = Tape & Reel (60 positions maximum)

LEAD STYLE	A
-01	(4.27) .168
-02	(7.21) .284

***Note:** -C Plating passes 10 year MFG testing

• Passes 10 year MFG

BSE	NO. OF POSITIONS PER ROW	01	PLATING OPTION	D	A	OTHER OPTION
Mates with: BTE	-020, -040, -060, -080, -100, -120		-F = Gold Flash on contact, Matte Tin on tail -L = 10 µ" (0.25 µm) Gold on contact, Matte Tin on tail -C* = Electro-Polished Selective 50 µ" (1.27 µm) min Au over 150 µ" (3.81 µm) Ni on Signal Pins in contact area, Matte Tin over 50 µ" (1.27 µm) min Ni on all solder tails			-TR = Tape & Reel (80 positions maximum)

***Note:** -C Plating passes 10 year MFG testing